

Customer No.: 31561
Docket No.: 13184-US-PA
Application No.: 10/710,696

REMARKS

Present Status of the Application

Claims 1-4, 6-14 and 17-21 are rejected under 35 U.S.C. 102(e) as being anticipated by Mund et al. (U.S. Pub. 2006/0030074; hereinafter Mund). Claim 5 is rejected under 35 U.S.C. 103(a) as being unpatentable over Mund in view of Kinoshita et al. (U. S. Pub. 2004/0232104; hereinafter Kinoshita). Applicants have amended independent claims 1 and 10. After entry of amendments, claims 1-14 and 17-21 remain pending in the present application, and reconsideration of those claims is respectfully requested.

About Amendments

Applicants have amended independent claims 1 and 10 to improve clarity. Further, as for example described in [0023] and FIG 1C, both of the glue and the spacers are directly contacting with the dielectric substrate and the wafer, so as to have constant gap. The spacers are surrounded by the glue and directly contact the substrate and the wafer. The amendments do not add new matter.

Discussion of Claim Rejections under 35 USC 102

Claims 1-4, 6-14 and 17-21 are rejected under 35 U.S.C. 102(e) as being anticipated by Mund. Applicants respectfully traverse the rejections for at least the reasons set forth below.

1. It is believed that independent claims 1 and 10 have clearly recited the distinct features.

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However, Applicants have amended independent claims 1 and 10 to respond the Office Action in "*Response to Arguments*".

In the amendments, the spacers are clearly inside the glue. Since the spacers hold the uniform distance between the wafer and the dielectric substrate, the grinding step is performed after attaching the dielectric substrate over the device on the wafer.

2. As stated in previous Response, the spacers 130 in FIG. 1C are surrounded by the glue to hold the substrate 140 before the substrate 140 is ground. The glue with the spacers can contact between the wafer and the dielectric substrate to provide a constant gap. Due to the holding effect by the spacers 130, the substrate 140 is ground without damaging the device 114.

3. In re Mund (Fig. 9), the bonding frame 310 is considered as the spacer of the present invention and the bonding locations 314 is considered as the glue of the present invention by the Office Action. In this manner, the glue 314 does not contain the spacer 310 in Mund.

Further, in paragraph [0111] of Mund, Mund only discloses that the glass substrate 302 is polished. In Fig. 9, the substrate 302 is serving as a base for bonding. Very possibly, the glass substrate 302 may have been polished before assembling the device with the second substrate 312.

However, in the present invention as the amended claim, the dielectric substrate is ground after being disposed over the device on the wafer.

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Apparently, Mund does not disclose the features of the present invention as recited in independent claims 1 and 10. With at least the same foregoing reasons, dependent claims 2-4, 6-9, 11-14 and 17-21 are distinguishable over prior art.

Discussion of Claim Rejections under 35 USC 103

Claim 5 is rejected under 35 U.S.C. 103(a) as being unpatentable over Mund in view of Kinoshita. Applicants respectively traverse the rejections for at least the reasons set forth below.

Mund does not disclose the features as recited in dependent claim 1 for at least the foregoing reasons.

Kinoshita does not disclose the missing features in Mund corresponding to independent claim 1 and therefore in dependent claim 5.

For at least the foregoing reasons, Applicant respectfully submits that independent claims 1 and 10 patently define over the prior art references, and should be allowed. For at least the same reasons, dependent claims 2-9, 11-14 and 17-21 patently define over the prior art references as well.

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CONCLUSION

For at least the foregoing reasons, it is believed that all the pending claims 1-14 and 17-21 of the invention patently define over the prior art and are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date :

June 1, 2007

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